

Listing of Claims:

1. (Currently amended) An electronic device, comprising:
a display unit; and
a host electrically connected to the display unit, comprising a module structure having a first substrate, at least one process unit, at least one heat-dissipating device and at least one second substrate, wherein the process unit is disposed on the first substrate, the heat-dissipating device is disposed on the first substrate relative to the process unit, and the second substrate is disposed on the first substrate relative to the process unit, and the second substrate and the first substrate have the same structure and texture.
2. (Original) The electronic device as claimed in claim 1, wherein the first substrate and the second substrate are formed from the same material.
3. (Original) The electronic device as claimed in claim 1, wherein the first substrate and the second substrate are formed by a multi-layer structure.
4. (Original) The electronic device as claimed in claim 1, wherein the first substrate comprises a plurality of connecting portions, and the heat-dissipating device is disposed on the connecting portions.
5. (Original) The electronic device as claimed in claim 1, wherein the process unit comprises CPU.
6. (Original) A module structure of an electronic device, comprising:
a first substrate;
a process unit disposed on the first substrate;
a heat-dissipating device disposed on the first substrate relative to the process unit; and
a second substrate disposed on the first substrate relative to the process unit, having the same structure and texture as the first substrate.

7. (Original) The module structure of the electronic device as claimed in claim 6, wherein the first substrate and the second substrate are formed from the same material.

8. (Original) The module structure of the electronic device as claimed in claim 6, wherein the first substrate and the second substrate are formed by a multi-layer structure.

9. (Original) The module structure of the electronic device as claimed in claim 6, wherein the first substrate comprises a plurality of connecting portions, and the heat-dissipating device is disposed on the connecting portions.

10. (Original) The module structure of the electronic device as claimed in claim 6, wherein the process unit comprises CPU.

11. (New) An electronic device, comprising:
a host comprising a module structure having a first substrate, at least one process unit, at least one heat-dissipating device and at least one second substrate, wherein the process unit is disposed on the first substrate, the heat-dissipating device is disposed on the first substrate relative to the process unit, the second substrate disposed on the first substrate relative to the process unit is connected to the heat-dissipating device, and the second substrate and the first substrate have the same structure and texture.

12. (New) The electronic device as claimed in claim 1, wherein the first substrate and the second substrate are formed from the same material.

13. (New) The electronic device as claimed in claim 1, wherein the first substrate and the second substrate are formed by a multi-layer structure.

14. (New) The electronic device as claimed in claim 1, wherein the first substrate comprises a plurality of connecting portions, and the heat-dissipating device is disposed on the connecting portions.

15. (New) The electronic device as claimed in claim 1, wherein the process unit comprises CPU.

16. (New) A module structure of an electronic device, comprising:
a first substrate;
a process unit disposed on the first substrate;
a heat-dissipating device disposed on the first substrate relative to the process unit; and
a second substrate disposed on the first substrate relative to the process unit and connected to the heat-dissipating device, wherein the second substrate has the same structure and texture as the first substrate.

17. (New) The module structure of the electronic device as claimed in claim 6, wherein the first substrate and the second substrate are formed from the same material.

18. (New) The module structure of the electronic device as claimed in claim 6, wherein the first substrate and the second substrate are formed by a multi-layer structure.

19. (New) The module structure of the electronic device as claimed in claim 6, wherein the first substrate comprises a plurality of connecting portions, and the heat-dissipating device is disposed on the connecting portions.

20. (New) The module structure of the electronic device as claimed in claim 6, wherein the process unit comprises CPU.